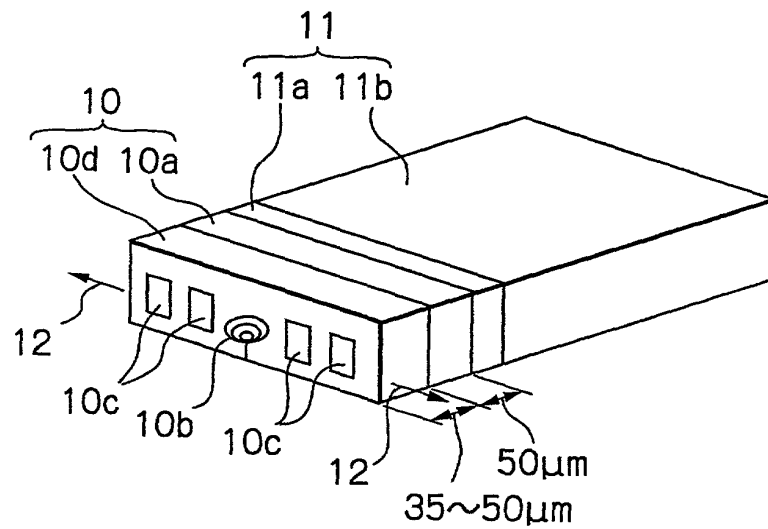


Fig. 1



S1



PREPARING OF
Al₂O₃-TiC WAFER 30

PREPARING OF ZrO_2
WAFER 35

FORMING OF THIN-FILM MAGNETIC HEAD ELEMENTS ON WAFER 30

FORMING OF ACTUATOR
LAYER 36 ON WAFER 35

THINNING OF WAFER 32 BY GRINDING ITS REAR SURFACE

CUTTING AND
SEPARATING OF WAFER
INTO INDIVIDUAL
ACTUATOR SECTIONS 38

CUTTING AND SEPARATING OF WAFER INTO INDIVIDUAL MAGNETIC HEAD SECTIONS 34

FIXING OF ACTUATOR
SECTION 38 TO REAR
SURFACE OF MAGNETIC
HEAD SECTION 34

Fig. 3

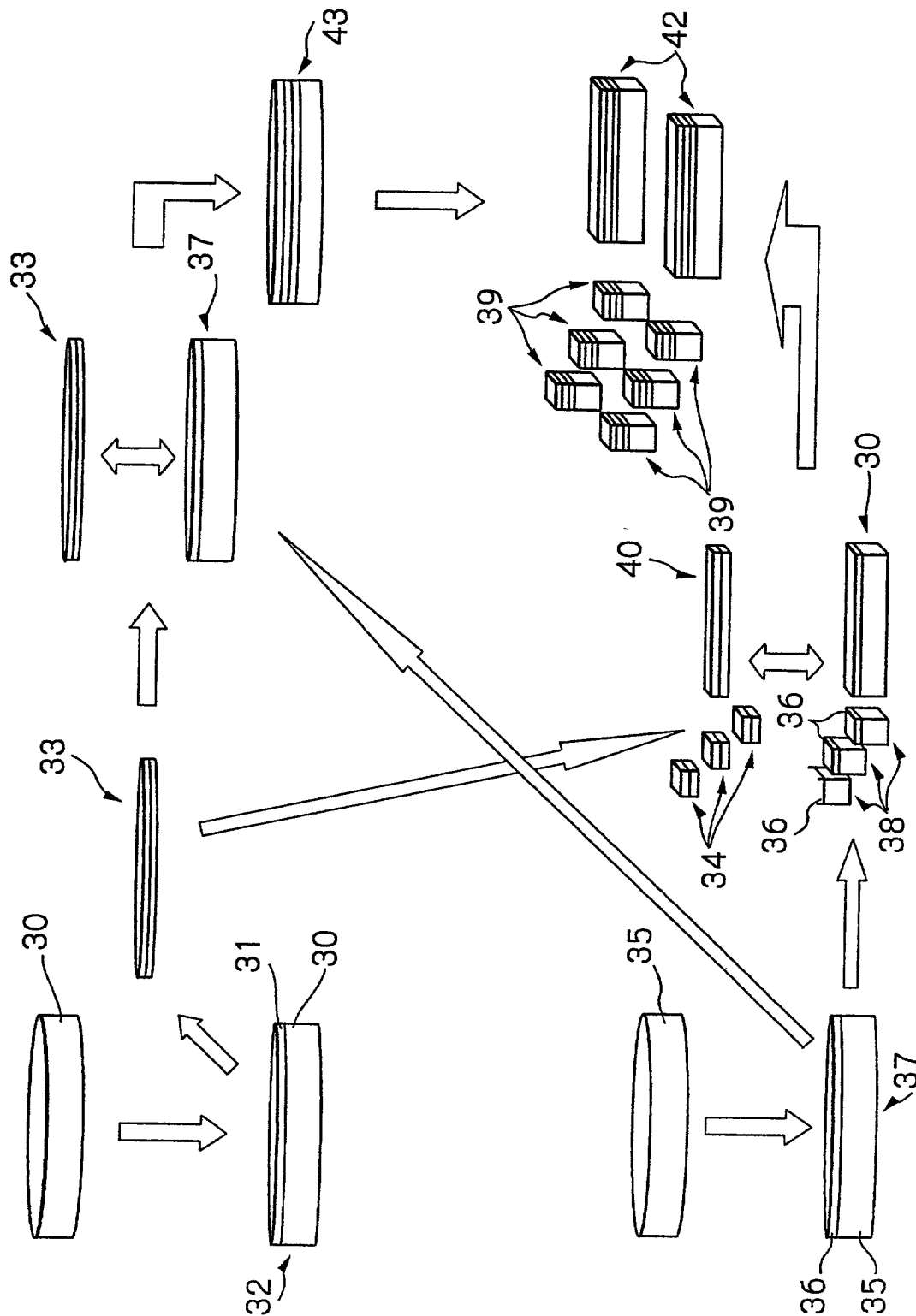
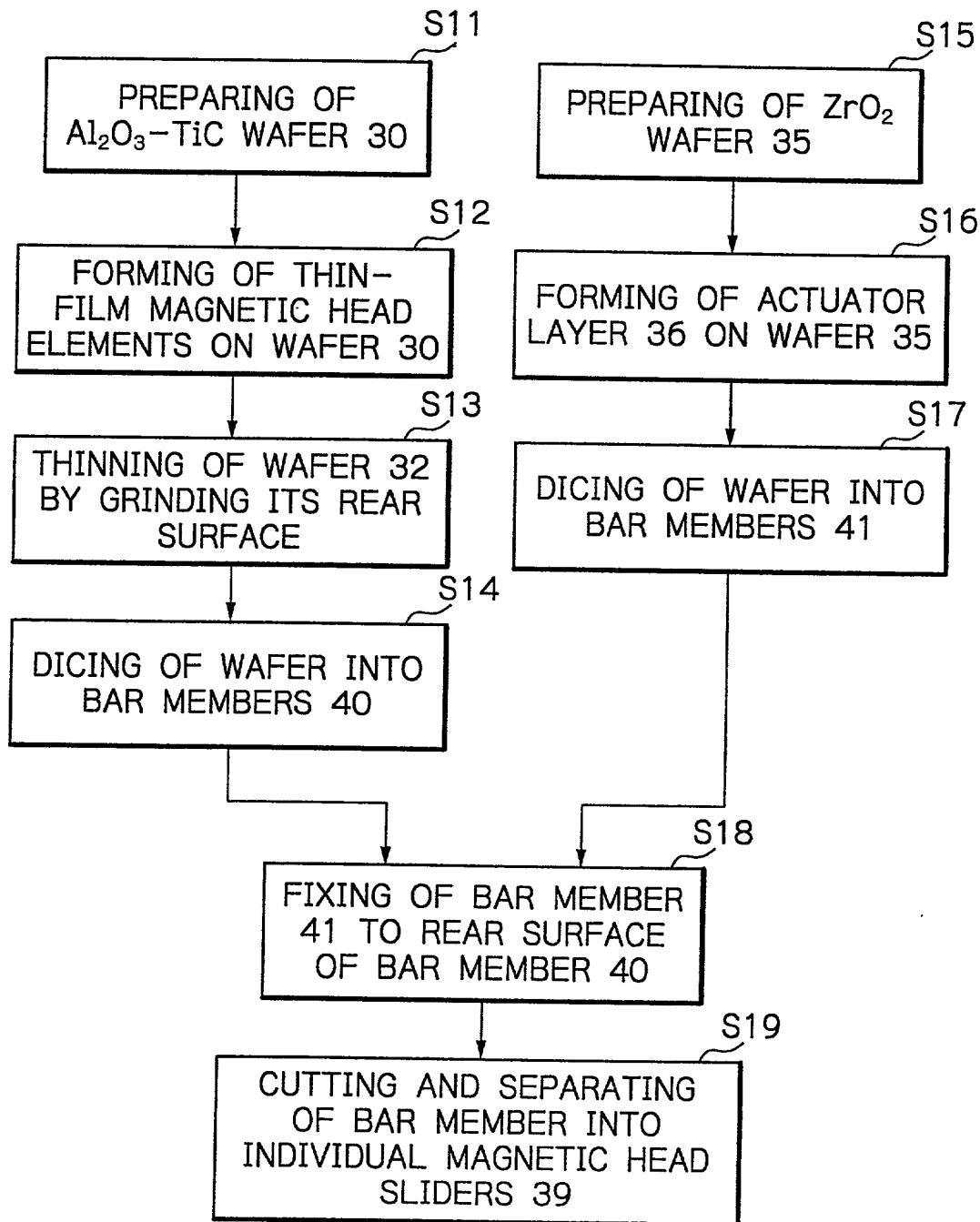


Fig. 4



20020703 070203

Fig. 5

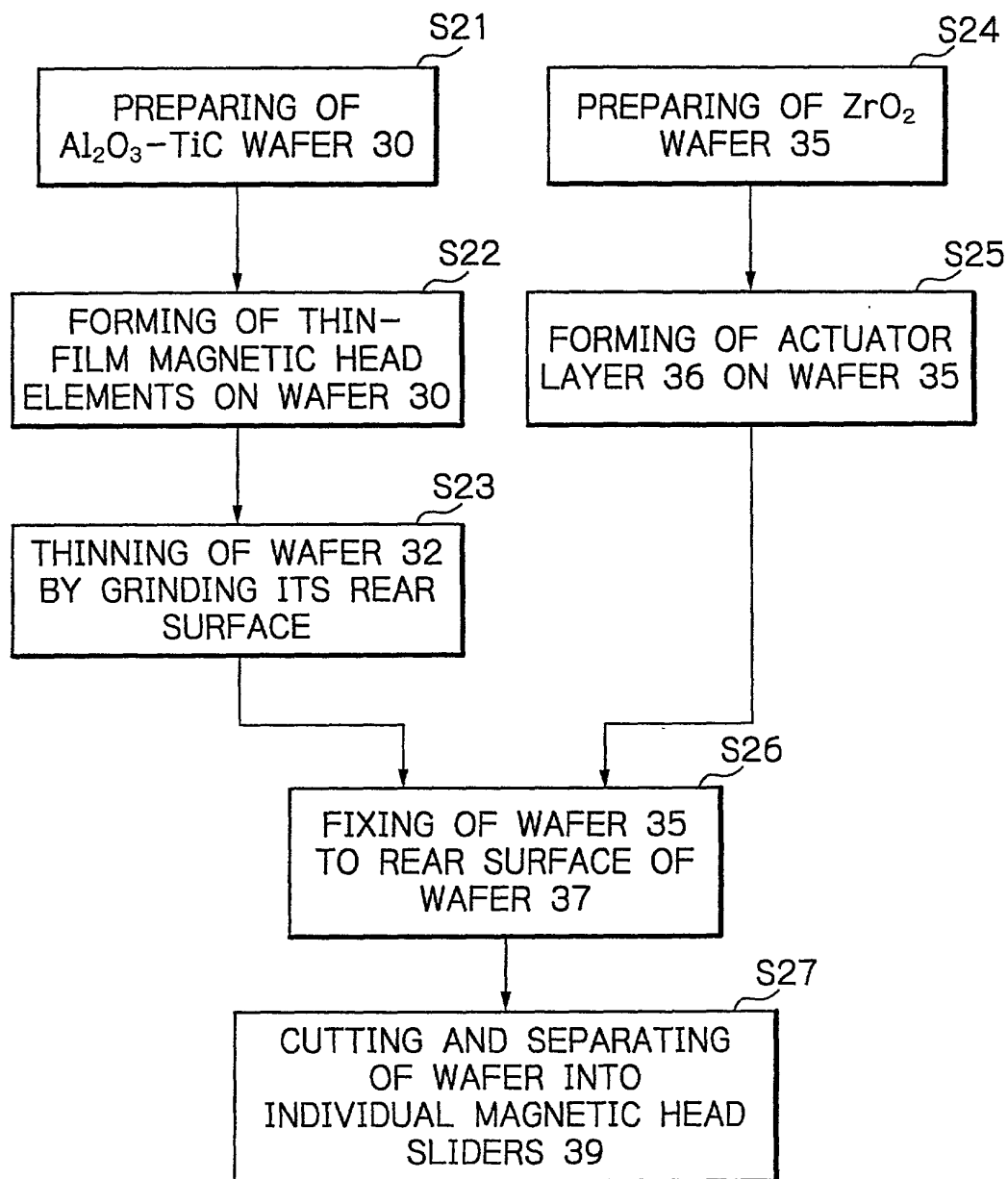


Fig. 6

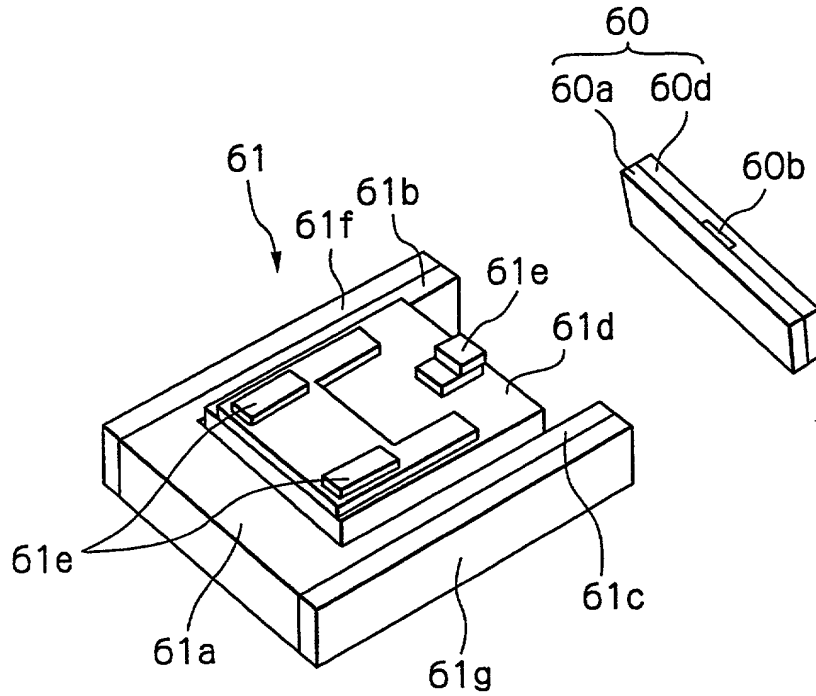
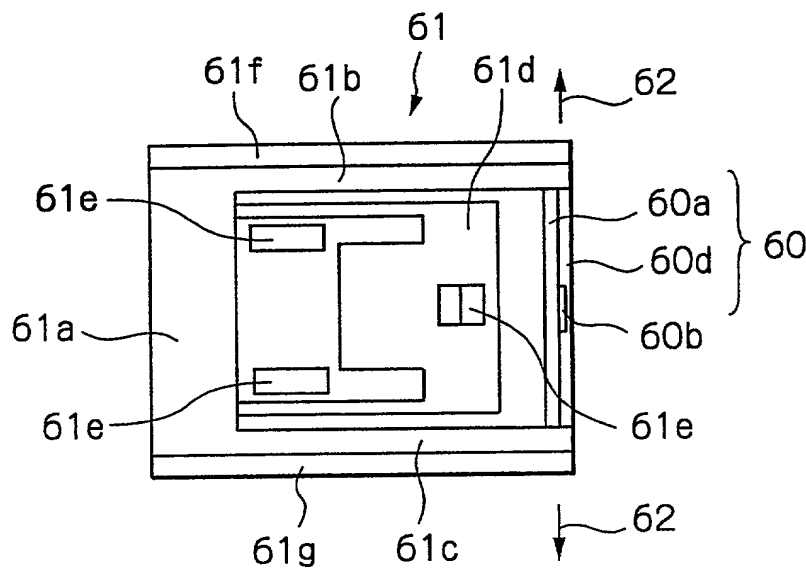


Fig. 7



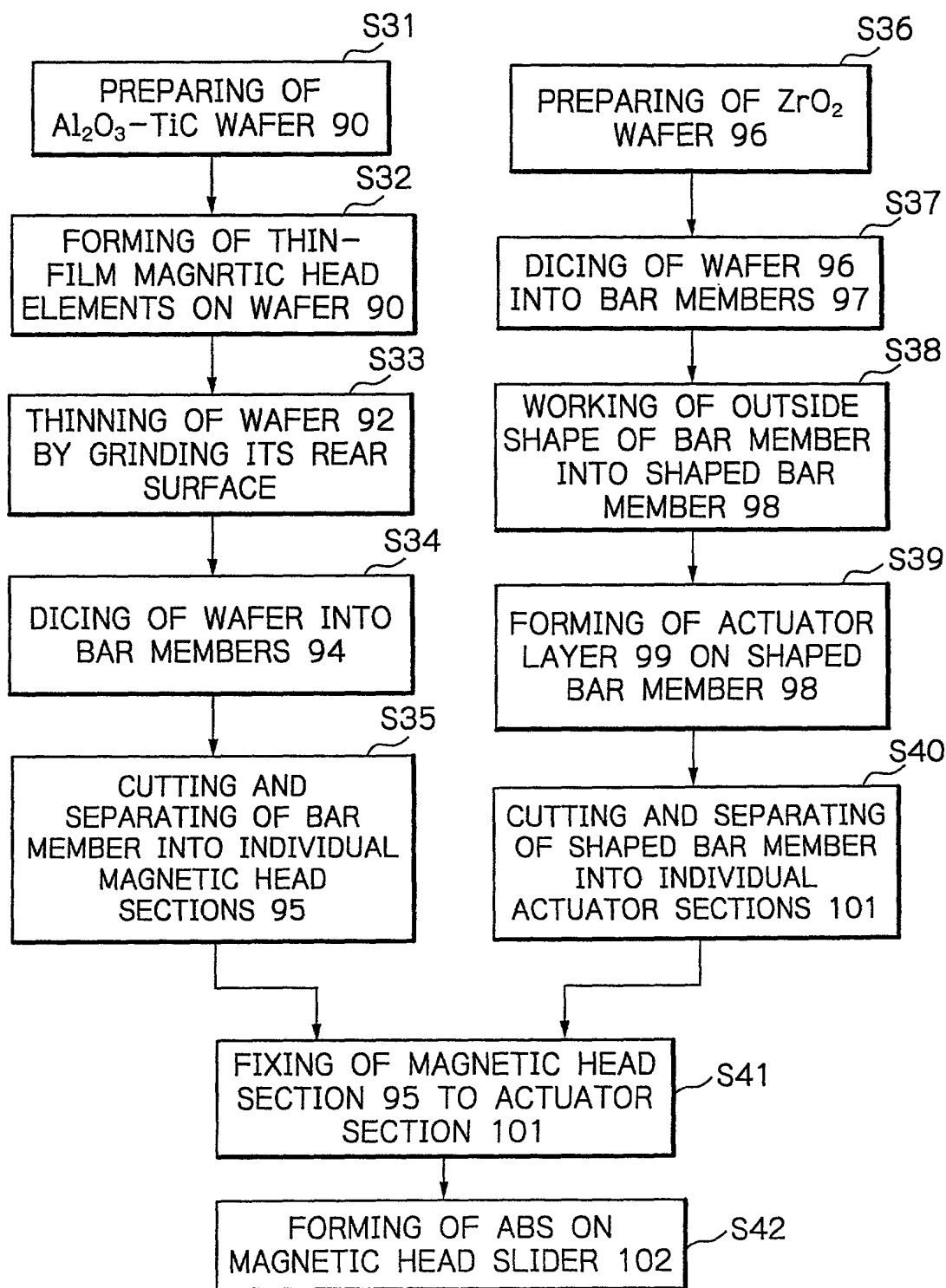


Fig. 9

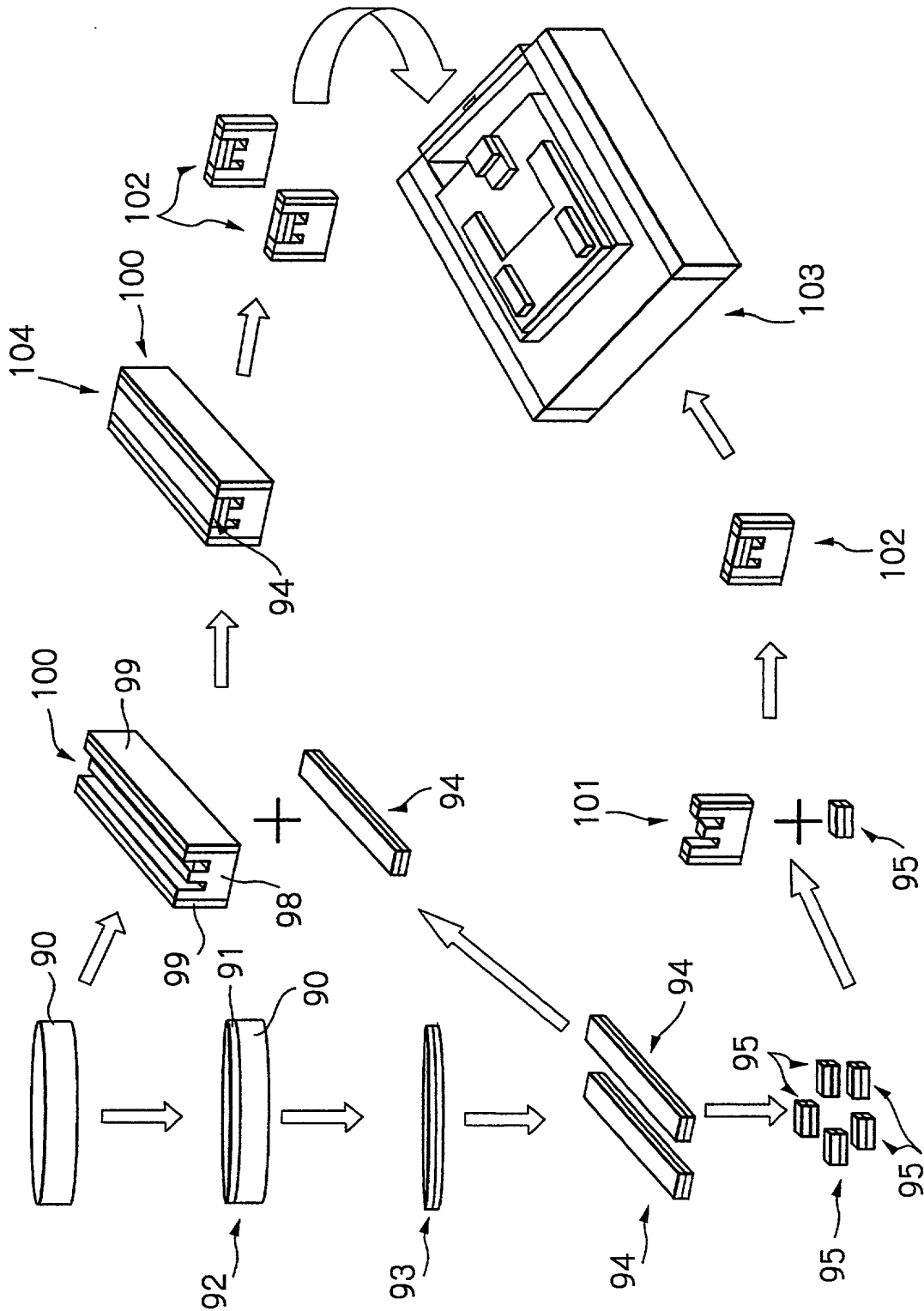


Fig. 10

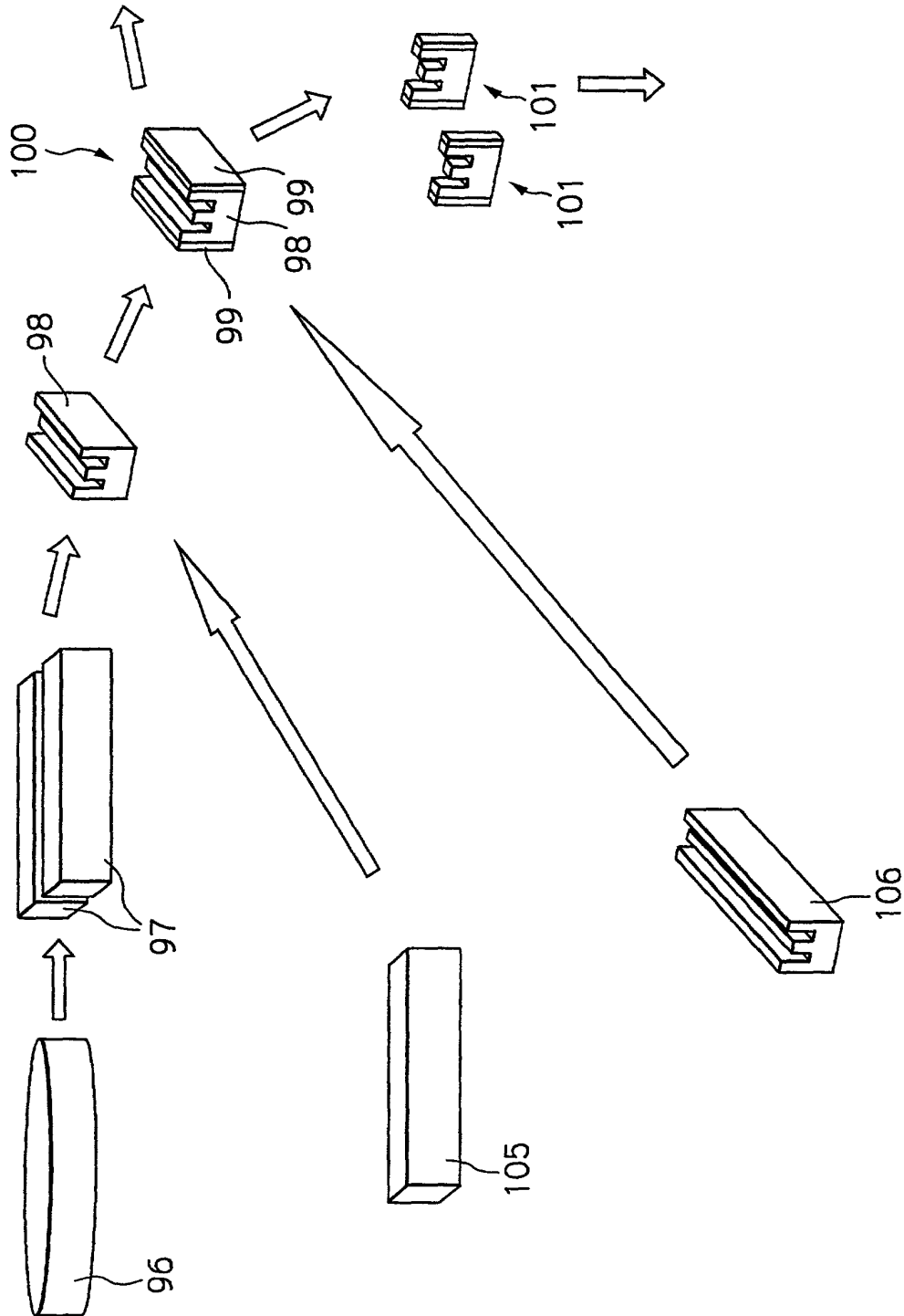


Fig. 11

